

# ABSTRACT

5 A solid or semi-solid thermoplastic adhesive  
adhered to a surface mount electronic device; an  
assembly made of at least a printed circuit board, a  
surface mount electronic device, solder joints  
providing a connection between the printed circuit  
board and the device, and solid thermoplastic  
adhesive joints attached to the device and the  
10 board. The thermoplastic adhesive is at least  
softened and applied to any available surface on the  
connecting substrate of the surface mounted  
electronic device. The thermoplastic adhesive is  
heated to a temperature sufficient to provide an  
15 adhesive joint between the organic surface and the  
board. There is also provided a thermoplastic  
adhesive composition having at least the following  
components:

20 (A) from 5% to 98% by weight of a functionalized  
polyolefin, and

(B) from 2% to 95% by weight of a polyamide  
compound.